

# 10V Drive Nch MOSFET

**R6046FNZ**

## ● Structure

## Silicon N-channel MOSFET

## ● Features

- 1) Low on-resistance.
  - 2) Low input capacitance.
  - 3) High ESD.

### ● Application

## Switching

- Packaging specifications

| Type     | Package                      | Bulk |
|----------|------------------------------|------|
| R6046FNZ | Code                         | -    |
|          | Basic ordering unit (pieces) | 360  |
|          | O                            |      |

- **Absolute maximum ratings** ( $T_a = 25^\circ\text{C}$ )

| Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ ) |            |           |             |                  |
|---|------------|-----------|-------------|------------------|
| Parameter   |            | Symbol    | Limits      | Unit             |
| Drain-source voltage                                  |            | $V_{DSS}$ | 600         | V                |
| Gate-source voltage                                   |            | $V_{GSS}$ | $\pm 30$    | V                |
| Drain current   | Continuous | $I_D$     | $\pm 46$    | A                |
|   | Pulsed     | $I_{DP}$  | $\pm 115$   | A                |
| Source current<br>(Body Diode)                        | Continuous | $I_S$     | 46          | A                |
|   | Pulsed     | $I_{SP}$  | 115         | A                |
| Avalanche current                                     |            | $I_{AS}$  | 23          | A                |
| Avalanche energy                                      |            | $E_{AS}$  | 142         | mJ               |
| Power dissipation                                     |            | $P_D$     | 120         | W                |
| Channel temperature                                   |            | $T_{ch}$  | 150         | $^\circ\text{C}$ |
| Range of storage temperature                          |            | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |

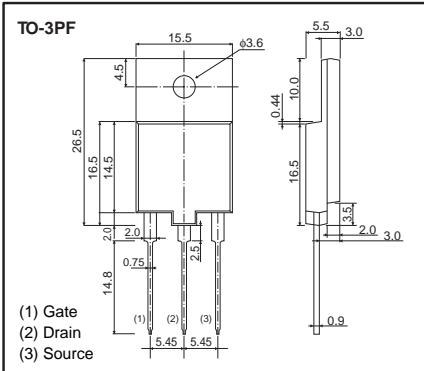
\*1 Pw≤10μs, Duty cycle≤1%

\*2 L = 500μH, V<sub>DD</sub>=50V, R<sub>G</sub>=25Ω, T<sub>ch</sub>=25°C

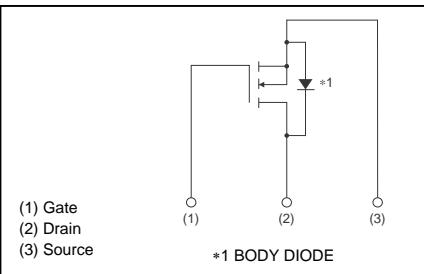
\*3 Limited only by maximum channel temperature allowed.

\*4 T<sub>C</sub>=25°C

● Dimensions (Unit : mm)



### ● Inner circuit



- Thermal resistance

| Parameter       | Symbol                 | Limits | Unit   |
|-----------------|------------------------|--------|--------|
| Channel to Case | R <sub>th (ch-c)</sub> | 1.04   | °C / W |

## ● Electrical characteristics (Ta = 25°C)

| Parameter                               | Symbol                            | Min. | Typ. | Max. | Unit | Conditions                                 |
|---|-----------------------------------|------|------|------|------|--|
| Gate-source leakage                     | I <sub>GSS</sub>                  | -    | -    | ±100 | nA   | V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V |
| Drain-source breakdown voltage          | V <sub>(BR)DSS</sub>              | 600  | -    | -    | V    | I <sub>D</sub> =1mA, V <sub>GS</sub> =0V   |
| Zero gate voltage drain current         | I <sub>DSS</sub>                  | -    | -    | 100  | μA   | V <sub>DS</sub> =600V, V <sub>GS</sub> =0V |
| Gate threshold voltage                  | V <sub>GS</sub> (th)              | 3.0  | -    | 5.0  | V    | V <sub>DS</sub> =10V, I <sub>D</sub> =1mA  |
| Static drain-source on-state resistance | R <sub>DS</sub> (on) <sup>*</sup> | -    | 75   | 93   | mΩ   | I <sub>D</sub> =23A, V <sub>GS</sub> =10V  |
| Forward transfer admittance             | Y <sub>fs</sub>  *                | 21   | 35   | -    | S    | V <sub>DS</sub> =10V, I <sub>D</sub> =23A  |
| Input capacitance                       | C <sub>iss</sub>                  | -    | 6100 | -    | pF   | V <sub>DS</sub> =25V                       |
| Output capacitance                      | C <sub>oss</sub>                  | -    | 3600 | -    | pF   | V <sub>GS</sub> =0V                        |
| Reverse transfer capacitance            | C <sub>rss</sub>                  | -    | 90   | -    | pF   | f=1MHz                                     |
| Turn-on delay time                      | t <sub>d(on)</sub> *              | -    | 77   | -    | ns   | V <sub>DD</sub> =300V, I <sub>D</sub> =23A |
| Rise time                               | t <sub>r</sub> *                  | -    | 150  | -    | ns   | V <sub>GS</sub> =10V                       |
| Turn-off delay time                     | t <sub>d(off)</sub> *             | -    | 230  | -    | ns   | R <sub>L</sub> =13.04Ω                     |
| Fall time                               | t <sub>f</sub> *                  | -    | 80   | -    | ns   | R <sub>G</sub> =10Ω                        |
| Total gate charge                       | Q <sub>g</sub> *                  | -    | 150  | -    | nC   | V <sub>DD</sub> =300V                      |
| Gate-source charge                      | Q <sub>gs</sub> *                 | -    | 40   | -    | nC   | I <sub>D</sub> =46A                        |
| Gate-drain charge                       | Q <sub>gd</sub> *                 | -    | 60   | -    | nC   | V <sub>GS</sub> =10V                       |

\*Pulsed

## ● Body diode characteristics (Source-Drain)

| Parameter             | Symbol            | Min. | Typ. | Max. | Unit | Conditions                                 |
|-----------------------|-------------------|------|------|------|------|--|
| Forward voltage       | V <sub>SD</sub> * | -    | -    | 1.5  | V    | I <sub>S</sub> =12.5A, V <sub>GS</sub> =0V |
| Reverse recovery time | t <sub>rr</sub> * | -    | 145  | -    | ns   | I <sub>S</sub> =46A, di/dt=100A/μs         |

\*Pulsed

●Electrical characteristic curves ( $T_a=25^\circ\text{C}$ )

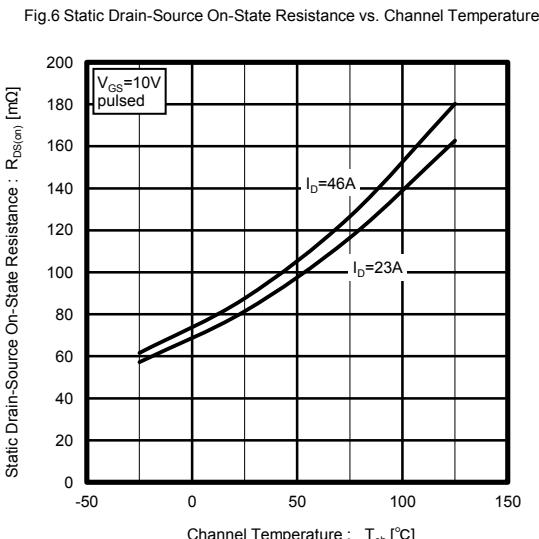
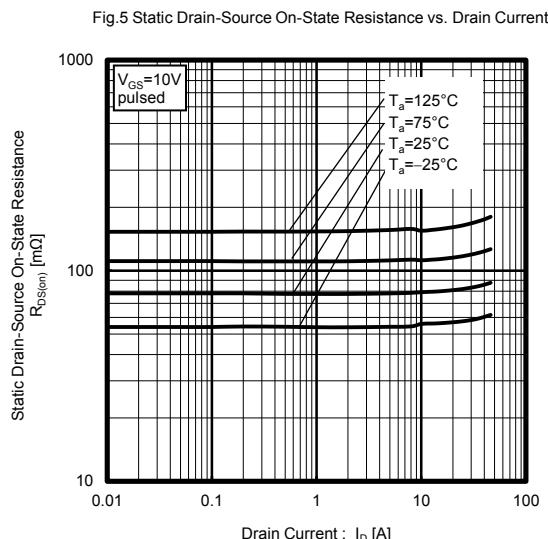
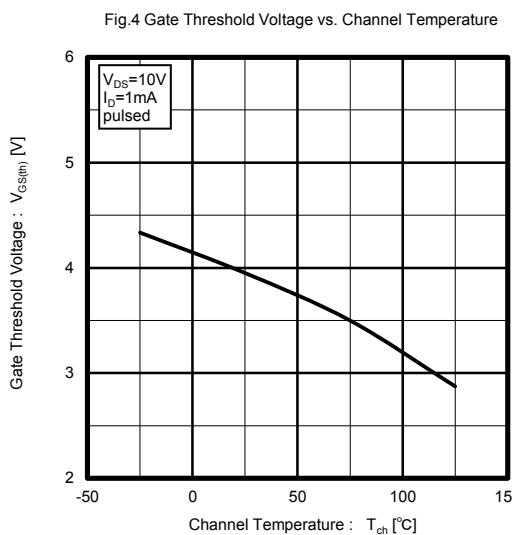
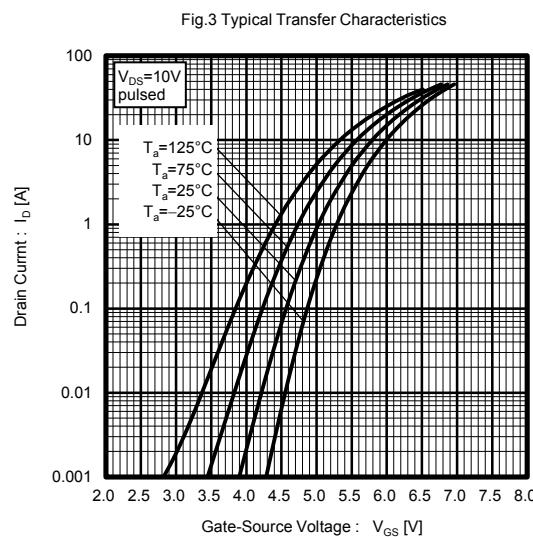
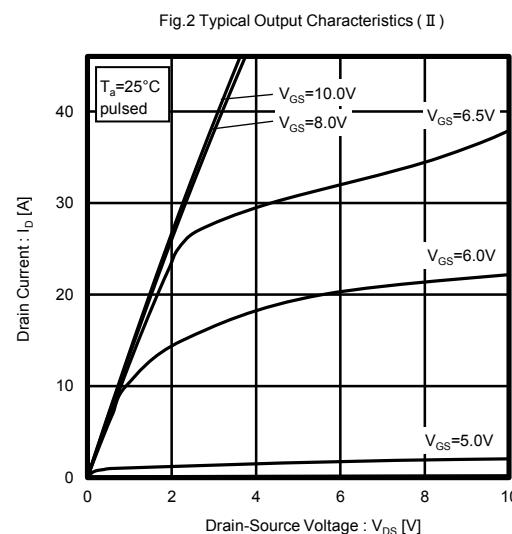
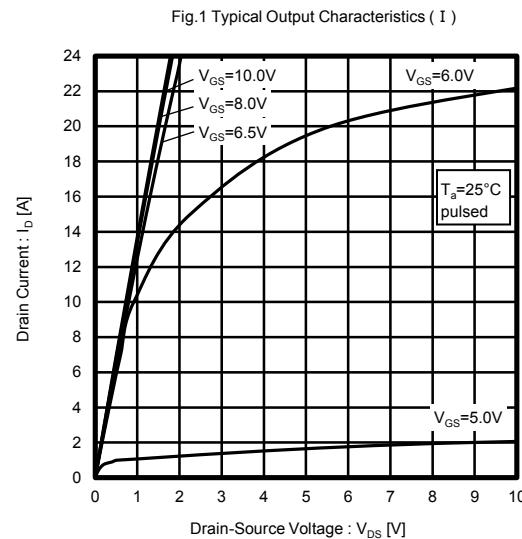


Fig.7 Forward Transfer Admittance vs. Drain Current

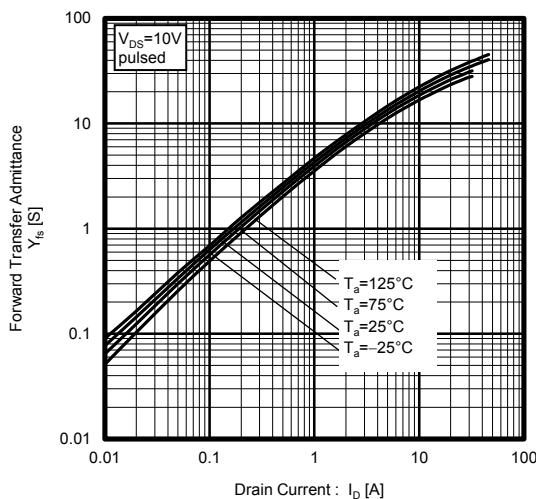


Fig.8 Source Current vs. Source-Drain Voltage

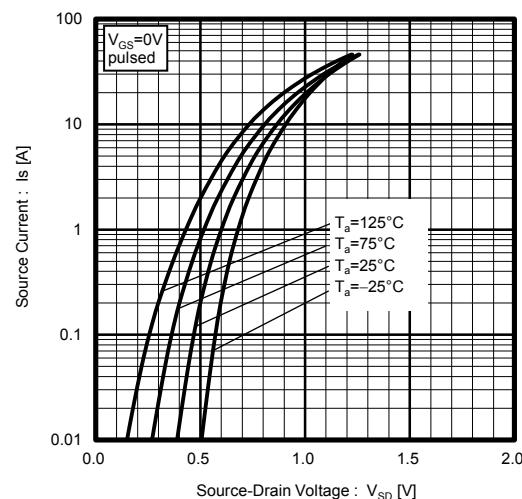


Fig.9 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

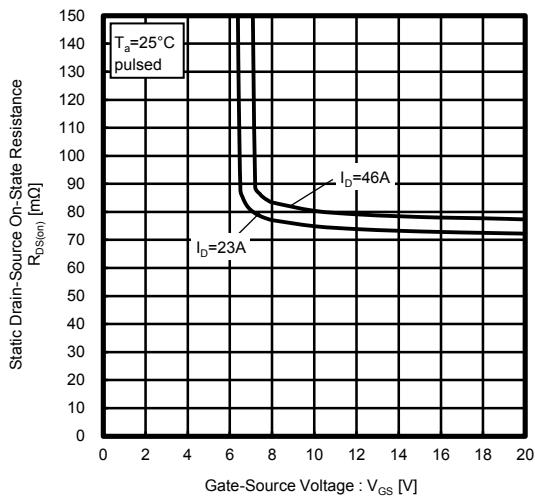


Fig.10 Switching Characteristics

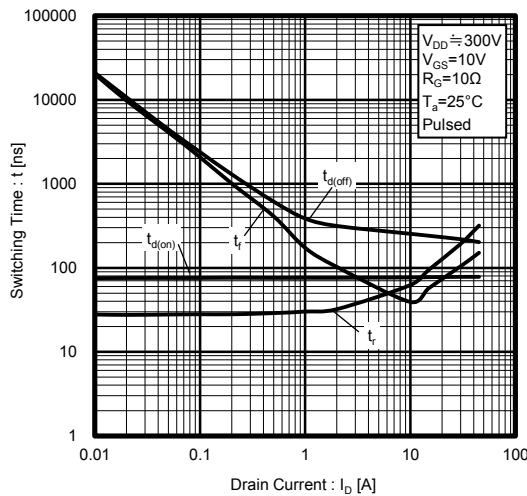


Fig.11 Dynamic Input Characteristics

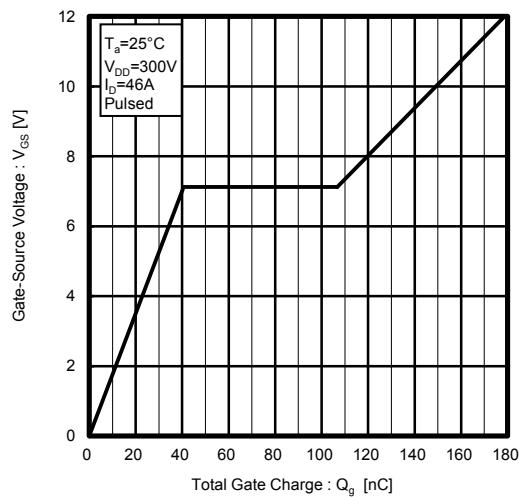


Fig.12 Typical Capacitance vs. Drain-Source Voltage

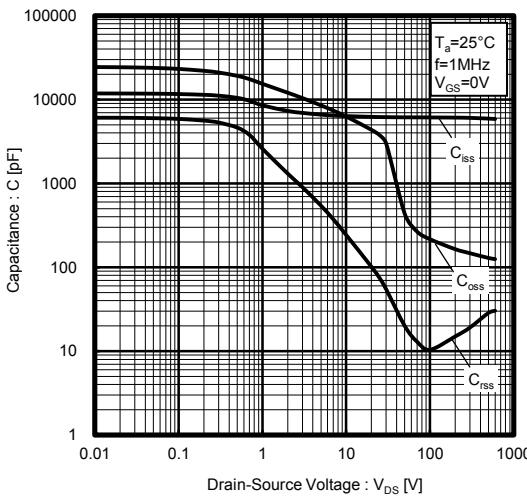
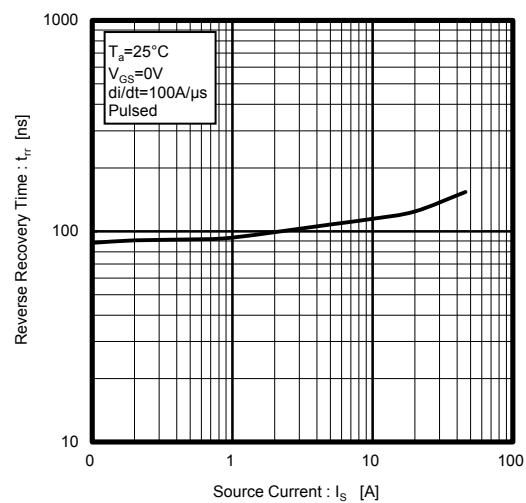


Fig.13 Reverse Recovery Time vs. Source Current



### ● Measurement circuits

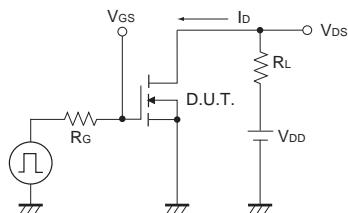


Fig.1-1 Switching Time Measurement Circuit

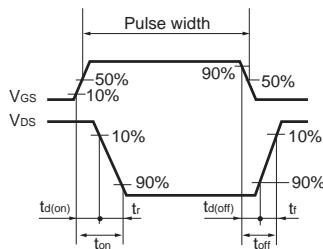


Fig.1-2 Switching Waveforms

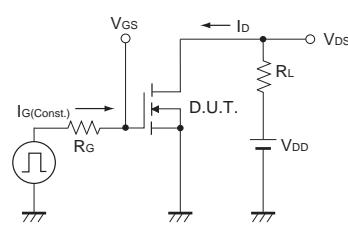


Fig.2-1 Gate Charge Measurement Circuit

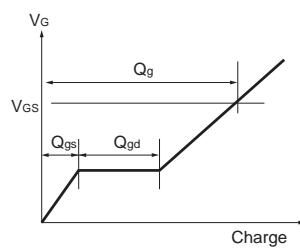


Fig.2-2 Gate Charge Waveform

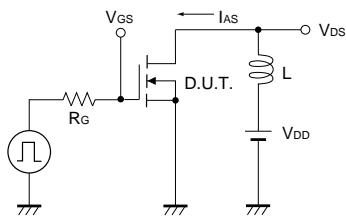


Fig.3-1 Avalanche Measurement Circuit

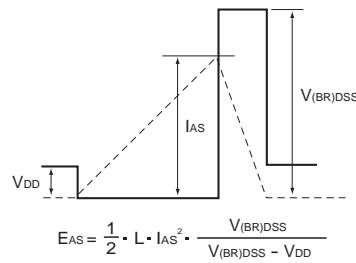


Fig.3-2 Avalanche Waveform

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